

# SSC8229GS1

#### **P-Channel Enhancement Mode MOSFET**

#### Features

V <sub>DS</sub>	$V_{GS}$	R <sub>DS(ON)</sub> Typ.	l <sub>D</sub>
-20V	±12V	21mΩ@-4V5	-29A
		30mΩ@-2V5	-29A

## > Description

This device is from Advanced Power innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

## Applications

- Load Switch
- NB battery
- DCDC conversion

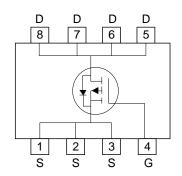
# > Ordering Information

Device	Package	Shipping
SSC8229GS1	SOP-8	4000/Reel

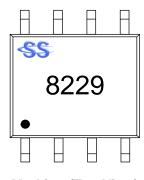
# Pin configuration



**SOP-8** 



Pin Configuration (Top View)



**Marking (Top View)** 



# ➤ Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DSS}$	-20	V
Gate-to-Source Voltage	$V_{GSS}$	±12	V
Continuous Drain Current <sup>C</sup>	I <sub>D</sub>	-29	Α
Continuous Drain Current a	I <sub>DSM</sub>	-7.9	Α
Pulsed Drain Current <sup>b</sup>	I <sub>DM</sub>	-119	Α
Power Dissipation <sup>c</sup>	P <sub>D</sub>	29.8	W
Power Dissipation <sup>a</sup>	P <sub>DSM</sub>	2.1	W
Operation junction temperature	TJ	-55 to 150	$^{\circ}\mathbb{C}$
Storage temperature range	T <sub>STG</sub>	-55 to 150	$^{\circ}\mathbb{C}$

## ➤ Thermal Resistance Ratings (T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit	
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance a	60	°C ////	
R <sub>0</sub> JC	Junction-to-Case Thermal Resistance	4.2	°C/W	

#### Note:

- a. The value of R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper,in a still air environment with T<sub>A</sub>=25 °C. The value in any given application depends on the user is specific board design. The current rating is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation  $P_D$  is based on  $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

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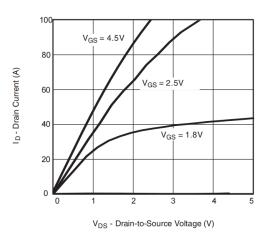


# $\succ$ Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

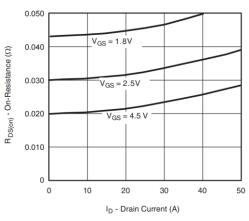
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_{D} = -250\mu A$	-20			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250uA$	-0.5	-0.7	-1	V
Drain Course On Registeres	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -12A		21	28	- mΩ
Drain-Source On-Resistance		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -8A		30	40	
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V			-1	μА
Gate-Source Leak Current	Igss	$V_{GS} = \pm 12V$ , $V_{DS} = 0V$			±100	nA
Transconductance	G <sub>FS</sub>	V <sub>DS</sub> = -5V, I <sub>D</sub> = -10A		25		S
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1A		-0.75	-1.3	V
Input Capacitance	Ciss	$V_{DS} = -10V, V_{GS} = 0V,$		1831		
Output Capacitance	Coss			207		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>	f = 1MHz		199		
Total Gate Charge	Q <sub>G</sub>	45777		84		
Gate to Source Charge	Q <sub>GS</sub>	$V_{GS} = -4.5V, V_{DS} = -10V,$		12		nC
Gate to Drain Charge	Q <sub>GD</sub>	I <sub>D</sub> = -12A		20		
Turn-on Delay Time	T <sub>D(ON)</sub>	$V_{GS} = -4.5V$ , $V_{DS} = -10V$ , $R_{L} = 3\Omega$ , $R_{G} = 1\Omega$ ,		15		
Rise Time	Tr			12		ns
Turn-off Delay Time	T <sub>D(OFF)</sub>			81		
Fall Time	T <sub>f</sub>	I <sub>D</sub> = -12A		68		



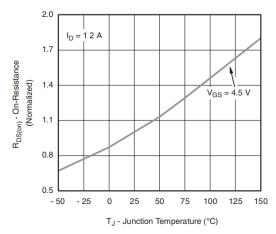
# > Typical Performance Characteristics (T<sub>A</sub>=25℃ unless otherwise noted)



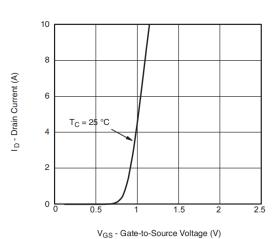
**Output Characteristics** 



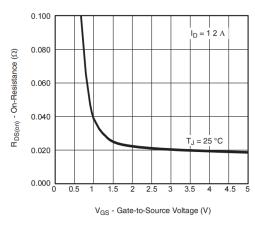
On-Resistance vs. Drain Current and Gate Voltage



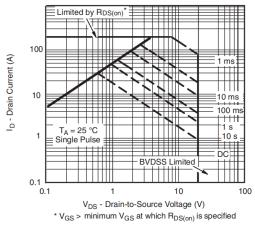
On-Resistance vs. Junction Temperature



Transfer Characteristics



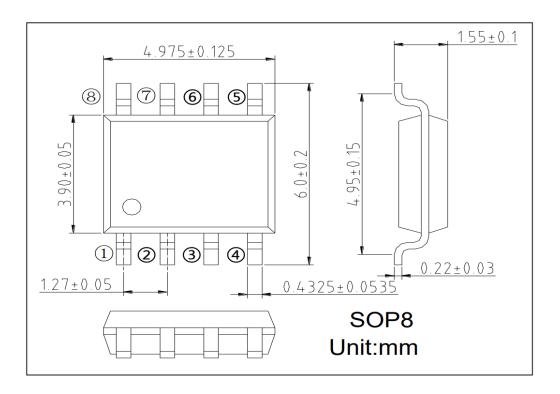
On-Resistance vs. Gate-to-Source Voltage



Safe Operating Area, Junction-to-Ambient



### Package Information



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